

67. The assembly according to claim 32, wherein each electronic module has a substrate that carries electronic elements, the electronic module being assembled to said plate via said substrate.

68. The assembly according to claim 32, wherein a slot is provided between the electronic module and the corresponding aperture, which houses the electronic module, said slot being interrupted by the means for securing the electronic module to said plate.

69. The assembly method according to claim 32, wherein each electronic module has at least one projecting zone, which is superposed on a peripheral area of the corresponding aperture in said plate, said projecting zone being bound to said peripheral area to secure the electronic module to the plate.

70. The assembly according to claim 32, wherein, at the periphery of each aperture, said plate has at least one project-

ing portion, which has a smaller thickness than that of said plate and is superposed on an edge zone of said electronic module, which is arranged in said aperture, said zone being secured to said projecting portion in order to secure the electronic module to the plate.

71. A method of manufacturing at least one card including the following steps:

making an intermediate product in accordance with claim 46;

depositing a resin over at least one of the top and bottom surfaces of said intermediate product, and

applying pressure on said resin, which is deposited on said intermediate product and which is then in a non-solid state to form at least one card with a flat external surface, said resin compensating for variations in thickness in said intermediate product.

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